

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all previous versions and listing of claims in the application.

Listing of Claims

Claims 1-15: Cancelled

16. (Withdrawn – Currently Amended) A method for producing a multilayer copper clad laminate by using the electrodeposited copper foil with carrier foil on which a resin layer for forming insulating layer is formed according to claim 18 ~~claim 1, which is characterized in that the method comprising: has process steps A to E as shown below; Step A:~~

a) drilling a double Double sided copper clad laminate to be an inner layer board is drilled to have [[a]] holes to be through-holes and/or via-holes, followed by treatment for removing residues ~~i.e. desmearing~~ if required; ~~–Step B:~~

b) plating a thin copper layer inside Inside a wall of the holes made in step a) ~~step A to be through-holes and/or via-holes are plated with thin copper layer to provide an~~ inter layer connection; ~~–Step C:~~

c) coating the double Double sided copper clad laminate ~~to be an inner layer board after finishing plating of thin copper layer for inter layer connection made in step b)~~ ~~step B is coated with a plating resist film and then exposing and developing~~ ~~expose and develop~~ the resist pattern to leave the resist film on the portion where no wiring is formed; ~~–Step D:~~

d) electrolytic copper plating on ~~On the~~ a portion without plating resist film of the double sided copper clad laminate made in step c) ~~to be an inner layer board where no wiring is formed; electrolytic copper plating is performed~~ to form inner layer wiring pattern and then removing the

plating resist ~~film is removed~~ followed by etching of the copper layer on the copper clad laminate to finish inner layer wiring board; ~~Step E:~~

e) laminating the ~~[[The]]~~ electrodeposited copper foil with carrier foil on which resin layer for forming insulating layer is formed ~~according to claim 1 is laminated~~ on one side or both side ~~sides~~ of the inner layer wiring board made in step d) ~~[[D]]~~ through hot press, followed by releasing of the carrier foil to get multilayer copper clad laminate which has 3 or more conductive layers.

17. (Withdrawn – Currently Amended) A method for producing a multilayer ~~copper~~ wiring board by etching the an outer layer copper foil on the multilayer copper clad laminate according to claim 16, comprising: ~~which is characterized in that the method has process steps 1 to 4 as shown below;~~ ~~Step 1:~~

a) drilling a multilayer ~~Multilayer~~ copper clad laminate ~~is drilled~~ to have ~~[[a]]~~ holes to be ~~[[a]]~~ blind via-holes, followed by a treatment for removing residues ~~i.e. desmearing~~ if required; ~~Step 2:~~

b) plating inside ~~inside wall~~ walls of the holes made in step 1 ~~is plated~~ with a thin copper layer to finish blind ~~via hole for performing via-holes to provide an~~ inter layer connection; ~~Step 3:~~

c) coating multilayer ~~Multilayer~~ copper clad laminate after finishing plating of thin copper layer for ~~inter layer connection~~ made in step b) ~~2 is coated~~ with a plating resist film and then exposing and developing ~~expose and develop~~ the resist pattern to leave the plating resist film on the portion where no wiring is formed; ~~Step 4:~~

d) electrolytic copper plating on ~~On the~~ a portion of the multilayer copper clad laminate without the plating resist film ~~where no wiring is formed, electrolytic copper plating is performed~~ to form outer layer wiring pattern and then removing the plating resist film ~~is removed~~ followed by etching of the copper layer on the multilayer copper clad laminate to finish multilayer wiring board.

18. (New) An electrodeposited copper foil with carrier foil on which a resin layer for forming an insulating layer is formed, comprising:

a carrier foil;

a bonding interface layer formed on top of the carrier foil;

an electrodeposited copper foil layer formed on top of the bonding interface layer having a surface roughness (Rzjis) on both sides of less than 2 μm ;

a rust proofing layer comprising a nickel-zinc alloy formed on top of the electrodeposited copper foil layer; and

a resin layer formed on top of the rust proofing layer,

wherein the resin layer comprises:

a) 20 to 80 parts by weight of an epoxy resin including a curing agent;

b) 20 to 80 parts by weight of a solvent soluble aromatic polyamide resin polymer

of; and

c) optionally a curing accelerator.

19. (New) The electrodeposited copper foil with carrier foil on which a resin layer for forming an insulating layer is formed according to claim 18, wherein the aromatic polyamide

resin polymer is obtained by a chemical reaction between an aromatic polyamide resin and a rubbery resin.

20. (New) The electrodeposited copper foil with carrier foil on which a resin layer for forming an insulating layer is formed according to claim 18, wherein the resin layer comprises a filler composed of a dielectric material.

21. (New) The electrodeposited copper foil with carrier foil on which a resin layer for forming an insulating layer is formed according to claim 18, wherein the resin layer comprises a skeletal material.

22. (New) The electrodeposited copper foil with carrier foil on which a resin layer for forming an insulating layer is formed according to claim 18, wherein the rustproofing layer additionally comprises a chromate layer.

23. (New) The electrodeposited copper foil with carrier foil on which a resin layer for forming an insulating layer is formed according to claim 18, wherein the nickel-zinc alloy of the rust proofing layer consists essentially of 50 to 99weight% of Ni, 1 to 50 weight% of Zn and unavoidable impurities.

24. (New) The electrodeposited copper foil with carrier foil on which a resin layer for forming an insulating layer is formed according to claim 18, comprising a silane coupling agent layer between the electrodeposited copper foil layer and the resin layer.

25. (New) The electrodeposited copper foil with carrier foil on which a resin layer for forming an insulating layer is formed according to claim 24, wherein the silane coupling agent layer is formed by using an amino-functional silane coupling agent or a mercapto-functional silane coupling agent.

26. (New) The electrodeposited copper foil with carrier foil on which a resin layer for forming an insulating layer is formed according to claim 18, wherein a thickness of the electrodeposited copper foil layer is 0.5 μm to 12 μm .

27. (New) A copper clad laminate obtained by using the electrodeposited copper foil with carrier foil on which a resin layer for forming an insulating layer is formed according to claim 18.

28. (New) A printed wiring board obtained by using the electrodeposited copper foil with carrier foil on which a resin layer for forming an insulating layer is formed according to claim 18.